Features

- Fast Read Access Time 70 ns
- Dual Voltage Range Operation

Unregulated Battery Power Supply Range, 2.7V to 3.6V or Standard 5V ± 10% Supply Range

- Pin Compatible with JEDEC Standard AT27C256
- Low Power CMOS Operation

20 $\,\mu$ A max. (less than 1 $\,\mu$ A typical) Standby for V_{CC} = 3.6V 29 mW max. Active at 5 MHz for V_{CC} = 3.6V

• JEDEC Standard Surface Mount Packages

32-Lead PLCC

28-Lead 330-mil SOIC

28-Lead TSOP

High Reliability CMOS Technology

2,000V ESD Protection

200 mA Latchup Immunity

- Rapid Programming Algorithm 100 µs/byte (typical)
- CMOS and TTL Compatible Inputs and Outputs

JEDEC Standard for LVTTL and LVBO

- Integrated Product Identification Code
- Commercial and Industrial Temperature Ranges

Description

The AT27BV256 is a high performance, low power, low voltage 262,144 bit one-time programmable read only memory (OTP EPROM) organized as 32K by 8 bits. It requires only one supply in the range of 2.7V to 3.6V in normal read mode operation, making it ideal for fast, portable systems using either regulated or unregulated battery power.

Atmel's innovative design techniques provide fast speeds that rival 5V parts while keeping the low power consumption of a 3V supply. At $V_{CC} = 2.7V$, any word can be accessed in less than 70 ns. With a typical power dissipation of only 18 mW at 5 MHz and $V_{CC} = 3V$, the AT27BV256 consumes less than one fifth the power of a standard 5V EPROM.

Pin Configurations

Pin Name	Function
A0 - A14	Addresses
O0 - O7	Outputs
CE	Chip Enable
ŌE	Output Enable
NC	No Connect

A7 VPP VCC A13
A12 NC A14

4 2 32 30
A6 5 3 1 31 29 A8
A5 6 28 A9
A4 7 27 A11
A3 8 26 NC
A2 9 25 OC
A1 10 24 A10
A0 11 23 CE
NC 12 22 07
OO 13 15 17 19 21
O6
14 16 18 20

PLCC Top View

O1 GND 03 05

Note: PLCC Package Pins 1 and 17 are DON'T CONNECT.

O2 NC O4

SOIC Top View

(continued)

ĺ		\neg		1	
VPP□	1		28	þ	VCC
A12 🗆	2		27	Þ	A14
A7 🗆	3		26	Þ	A13
A6 □	4		25	Þ	A8
A5 □	5		24	Þ	Α9
A4 □	6		23	Þ	A11
АЗ □	7		22	Þ	OE
A2 🗆	8		21	Þ	A10
A1 🗆	9		20		CE
A0 🗆	10		19	Þ	07
00 🗆	11		18	Þ	06
01 🗆	12		17	Þ	O5
02 🗆	13		16	Þ	04
GND □	14		15	Þ	О3

TSOP Top View

Type 1

OE	f		22	21		È	<u></u>	A10
A9 ¹	A11 🗄	23	24	19	20	Ĕ	CE	07
A13	A8 🗄	25	26	17	18	В	O6	O5
vcc'	A14	27	28	15	16	Ė	O4	03
	VPP}-	1			14	Ē	GND	
A12	A7 🗄	3	2	13	12	Б	01	O2
A6	A5 =	5	4	11	10	R	A0	O0
A4	9	7	6	9	8	Ē	A2	A1
	A3 □				- 0	Ъ,	72	

256K (32K x 8)
Unregulated
Battery-Voltage
High Speed
OTP
CMOS EPROM

0601A





Description (Continued)

Standby mode supply current is typically less than 1 μ A at 3V. The AT27BV256 simplifies system design and stretches battery lifetime even further by eliminating the need for power supply regulation.

The AT27BV256 is available in industry standard JEDEC-approved one-time programmable (OTP) plastic PLCC, SOIC and TSOP packages. All devices feature two-line control (CE, OE) to give designers the flexibility to prevent bus contention.

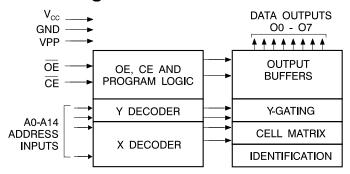
The AT27BV256 operating with V_{CC} at 3.0V produces TTL level outputs that are compatible with standard TTL logic devices operating at V_{CC} = 5.0V. At V_{CC} = 2.7V, the part is compatible with JEDEC approved low voltage battery operation (LVBO) interface specifications. The device is also capable of standard 5-volt operation making it ideally suited for dual supply range systems or card products that are pluggable in both 3-volt and 5-volt hosts.

Atmel's AT27BV256 has additional features to ensure high quality and efficient production use. The Rapid[™] Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100 μs/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry standard programming equipment to select the proper programming algorithms and voltages. The AT27BV256 programs exactly the same way as a standard 5V AT27C256R and uses the same programming equipment.

System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed data sheet limits, resulting in device non-conformance. At a minimum, a 0.1 μ F high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7 μ F bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

Block Diagram



Absolute Maximum Ratings*

Temperature Under Bias40°C to +85°C	
Storage Temperature65°C to +125°C	
Voltage on Any Pin with Respect to Ground2.0V to +7.0V (1)	
Voltage on A9 with Respect to Ground2.0V to +14.0V (1)	
V _{PP} Supply Voltage with Respect to Ground2.0V to +14.0V ⁽¹⁾	

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: 1. Minimum voltage is -0.6V dc which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V_{CC} + 0.75V dc which may be exceeded if certain precautions are observed (consult application notes) and which may overshoot to +7.0V for pulses of less than 20 ns.

Operating Modes

Mode \ Pin	CE	OE	Ai	V_PP	Vcc	Outputs
Read (2)	VIL	VIL	Ai	Vcc	Vcc (2)	Dout
Output Disable (2)	VIL	V_{IH}	X ⁽¹⁾	Vcc	Vcc (2)	High Z
Standby (2)	VIH	Χ	Х	Vcc	Vcc (2)	High Z
Rapid Program (3)	V_{IL}	V_{IH}	Ai	V_{PP}	Vcc (3)	D _{IN}
PGM Verify (3)	Χ	V_{IL}	Ai	V_{PP}	Vcc (3)	D _{OUT}
Optional PGM Verify (3)	VIL	V_{IL}	Ai	Vcc	Vcc (3)	Douт
PGM Inhibit (3)	V_{IH}	V_{IH}	Χ	V_{PP}	Vcc (3)	High Z
Product Identification (3, 5)	VIL	V _{IL}	A9 = V _H ⁽⁴⁾ A0 = V _{IH} or V _{IL} A1 - A14 = V _{IL}	Vcc	V _{CC} (3)	Identification Code

Notes: 1. X can be V_{IL} or V_{IH}.

- 2. Read, output disable, and standby modes require, $2.7V \le V_{CC} \le 3.6V$, or $4.5V \le V_{CC} \le 5.5V$.
- Refer to Programming Characteristics. Programming modes require V_{CC} = 6.5V.
- 4. $V_H = 12.0 \pm 0.5 V$.
- 5. Two identifier bytes may be selected. All Ai inputs are held low (V_{IL}), except A9 which is set to V_H and A0 which is toggled low (V_{IL}) to select the Manufacturer's Identification byte and high (V_{IH}) to select the Device Code byte.





DC and AC Operating Conditions for Read Operation

	AT27BV256								
	-70	-90	-12	-15					
Operating Temperature (Case) Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C					
Operating Temperature (Case) Com. Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C					
Van Bower Supply	2.7V to 3.6V	2.7V to 3.6V	2.7V to 3.6V	2.7V to 3.6V					
V _{CC} Power Supply	5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%					

DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
V _{CC} = 2	.7V to 3.6V				
ILI	Input Load Current	V _{IN} = 0V to V _{CC}		±1	μΑ
ILO	Output Leakage Current	$V_{OUT} = 0V$ to V_{CC}		±5	μΑ
I _{PP1} (2)	V _{PP} ⁽¹⁾ Read/Standby Current	VPP = VCC		10	μΑ
	V _{CC} ⁽¹⁾ Standby Current	I_{SB1} (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		20	μΑ
ISB	VCC > Standby Current	I _{SB2} (TTL), \overline{CE} = 2.0 to V _{CC} + 0.5V		100	μΑ
Icc	Vcc Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}, V_{CC} = V_{IL}$	= 3.6V	8	mA
\/	Input Low Voltage	V _{CC} = 3.0 to 3.6V	-0.6	0.8	V
V _{IL}	Input Low Voltage	V _{CC} = 2.7 to 3.6V	-0.6	0.2 x V _{CC}	V
VIH	Input High Voltage	V _{CC} = 3.0 to 3.6V	2.0	V _{CC} + 0.5	V
VIH	Input High Voltage	V _{CC} = 2.7 to 3.6V	0.7 x Vcc	Vcc + 0.5	V
		I _{OL} = 2.0 mA		0.4	V
V_{OL}	Output Low Voltage	I _{OL} = 100 μA		0.2	V
		$I_{OL} = 20 \mu A$		0.1	V
		IOH = -2.0 mA	2.4		V
Vон	Output High Voltage	IOH = -100 μA	Vcc - 0.2		V
		I _{OH} = -20 μA	V _{CC} - 0.1		V
$V_{CC} = 4$.5V to 5.5V				
ILI	Input Load Current	V _{IN} = 0V to V _{CC}		±1	μΑ
ILO	Output Leakage Current	Vout = 0V to Vcc		±5	μΑ
I _{PP1} (2)	V _{PP} ⁽¹⁾ Read/Standby Current	V _{PP} = V _{CC}		10	μΑ
I _{SB}	V _{CC} ⁽¹⁾ Standby Current	I_{SB1} (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μΑ
128	VCC Standby Current	I_{SB2} (TTL), $\overline{CE} = 2.0$ to $V_{CC} + 0.5V$		1	mA
Icc	V _{CC} Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$		20	mA
V_{IL}	Input Low Voltage		-0.6	8.0	V
VIH	Input High Voltage		2.0	Vcc + 0.5	V
VoL	Output Low Voltage	$I_{OL} = 2.1 \text{ mA}$		0.4	V
VoH	Output High Voltage	$I_{OH} = -400 \mu A$	2.4		V

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} , and removed simultaneously with or after V_{PP} .

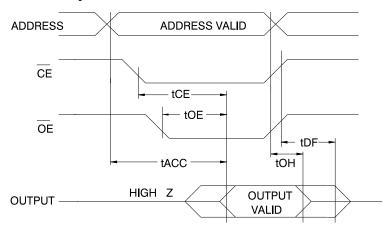
^{2.} V_{PP} may be connected directly to V_{CC} , except during programming. The supply current would then be the sum of I_{CC} and I_{PP} .

AC Characteristics for Read Operation ($V_{CC} = 2.7V$ to 3.6V and 4.5V to 5.5V)

			AT27BV256								
			-7	70	-9	90	-	12		15	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Min	Max	Units
t _{ACC} (3)	Address to Output Delay	$\overline{CE} = \overline{OE} = V_{IL}$		70		90		120		150	ns
t _{CE} (2)	CE to Output Delay	OE = VIL		70		90		120		150	ns
toE (2, 3)	OE to Output Delay	CE = V _{IL}		50		50		50		60	ns
t _{DF} (4, 5)	OE or CE High to Output Float, whichever occurred first			40		40		40		50	ns
tон	Output Hold from Address, \overline{CE} or \overline{OE} , whichever occurred first		0		0		0		0		ns

Notes: 2, 3, 4, 5. - see AC Waveforms for Read Operation.

AC Waveforms for Read Operation (1)



Notes: 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.

- 2. OE may be delayed up to t_{CE}-t_{OE} after the falling edge of CE without impact on t_{CE}.
- 3. OE may be delayed up to tACC-tOE after the address is valid without impact on tACC.
- 4. This parameter is only sampled and is not 100% tested.
- Output float is defined as the point when data is no longer driven.
- 6. When reading a 27BV256, a 0.1 μF capacitor is required across V_{CC} and ground to supress spurious voltage transients.



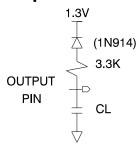


Input Test Waveform and Measurement Level

AC DRIVING LEVELS 0.45V 2.0 AC MEASUREMENT LEVEL

 t_R , $t_F < 20$ ns (10% to 90%)

Output Test Load



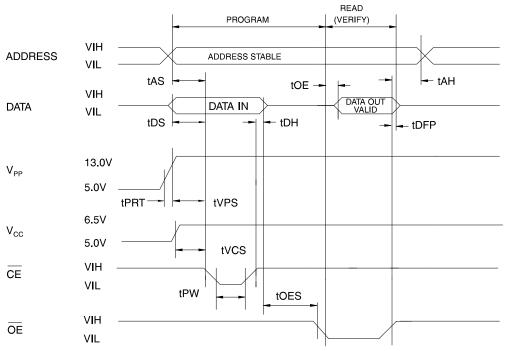
Note: CL = 100 pF including jig capacitance.

Pin Capacitance (f = 1 MHz, T = 25°C) (1)

	Тур	Max	Units	Conditions
C _{IN}	4	8	pF	$V_{IN} = 0V$
Cout	8	12	pF	$V_{OUT} = 0V$

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

Programming Waveforms (1)



Notes: 1. The Input Timing Reference is 0.8V for V_{IL} and 2.0V for $V_{IH}.$

- 2. toe and toep are characteristics of the device but must be accommodated by the programmer.
- 3. When programming the AT27BV256 a 0.1 μ F capacitor is required across V_{PP} and ground to suppress spurious voltage transients.

DC Programming Characteristics

TA = 25 $\pm~$ 5°C, V $_{CC}$ = 6.5 $\pm~$ 0.25V, V $_{PP}$ = 13.0 $\pm~$ 0.25V

		Test	Li	mits	
Symbol	Parameter	Conditions	Min	Max	Units
ILI	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μΑ
VIL	Input Low Level		-0.6	0.8	V
VIH	Input High Level		2.0	V _{CC} + 0.5	V
VoL	Output Low Voltage	$I_{OL} = 2.1 \text{ mA}$		0.4	V
Vон	Output High Voltage	$I_{OH} = -400 \mu A$	2.4		V
I _{CC2}	V _{CC} Supply Current (Program and Verify)			25	mA
I _{PP2}	V _{PP} Current	CE = V _{IL}		25	mΑ
VID	A9 Product Identification Voltage		11.5	12.5	V





AC Programming Characteristics

 T_{A} = 25 \pm 5°C, V_{CC} = 6.5 \pm 0.25V, V_{PP} = 13.0 \pm 0.25V

Sym- bol	Test Parameter Conditions* (1)	Lir Min	nits Max	Units
tas	Address Setup Time	2		μS
toes	OE Setup Time	2		μS
t _{DS}	Data Setup Time	2		μS
tah	Address Hold Time	0		μS
tDH	Data Hold Time	2		μS
t _{DFP}	OE High to Out- put Float Delay (2)	0	130	ns
t _{VPS}	V _{PP} Setup Time	2		μS
tvcs	V _{CC} Setup Time	2		μS
tpw	CE Program Pulse Width (3)	95	105	μS
toE	Data Valid from OE (2)		150	ns
tprt	V _{PP} Pulse Rise Time During Programming	50		ns

*AC Conditions of Test:

Input Rise and Fall Times (10% to 90%)......20 ns Input Pulse Levels.................0.45V to 2.4V Input Timing Reference Level......0.8V to 2.0V Output Timing Reference Level......0.8V to 2.0V

- Notes: 1. V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after VPP.
 - 2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven —see timing diagram.
 - 3. Program Pulse width tolerance is 100 μ sec \pm 5%.

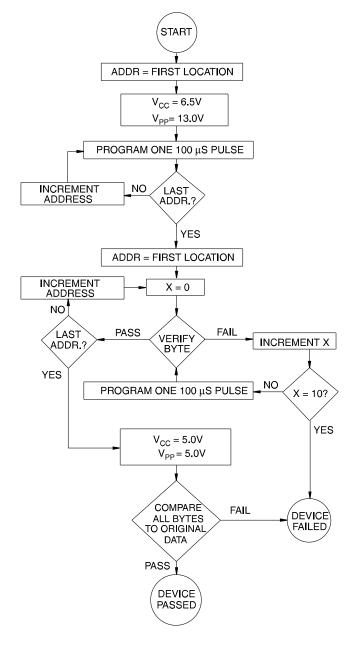
Atmel's 27BV256 Integrated (1) Product Identification Code

		Pins						Hex		
Codes	A0	07	06	O5	04	О3	02	01	00	Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	1	0	0	0	1	1	0	0	8C

Note: 1. The AT27BV256 has the same Product Identification Code as the AT27C256R. Both are programming compatible.

Rapid Programming Algorithm

A 100 µs $\overline{\text{CE}}$ pulse width is used to program. The address is set to the first location. VCC is raised to 6.5V and VPP is raised to 13.0V. Each address is first programmed with one 100 us CE pulse without verification. Then a verification / reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100 µs pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. VPP is then lowered to 5.0V and VCC to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.



Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ondonium Code	Doolsons	On anotion Decree
	Active	Standby	Ordering Code	Package	Operation Range
70	8	0.02	AT27BV256-70JC AT27BV256-70RC AT27BV256-70TC	32J 28R 28T	Commercial (0°C to 70°C)
	8	0.02	AT27BV256-70JI AT27BV256-70RI AT27BV256-70TI	32J 28R 28T	Industrial (-40°C to 85°C)
90	8	0.02	AT27BV256-90JC AT27BV256-90RC AT27BV256-90TC	32J 28R 28T	Commercial (0°C to 70°C)
	8	0.02	AT27BV256-90JI AT27BV256-90RI AT27BV256-90TI	32J 28R 28T	Industrial (-40°C to 85°C)
120	8	0.02	AT27BV256-12JC AT27BV256-12RC AT27BV256-12TC	32J 28R 28T	Commercial (0°C to 70°C)
	8	0.02	AT27BV256-12JI AT27BV256-12RI AT27BV256-12TI	32J 28R 28T	Industrial (-40°C to 85°C)
150	8	0.02	AT27BV256-15JC AT27BV256-15RC AT27BV256-15TC	32J 28R 28T	Commercial (0°C to 70°C)
	8	0.02	AT27BV256-15JI AT27BV256-15RI AT27BV256-15TI	32J 28R 28T	Industrial (-40°C to 85°C)

Package Type					
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)				
28R	28 Lead, 0.330" Wide, Plastic Gull Wing Small Outline (SOIC)				
28T	28 Lead, Plastic Thin Small Outline Package (TSOP)				

